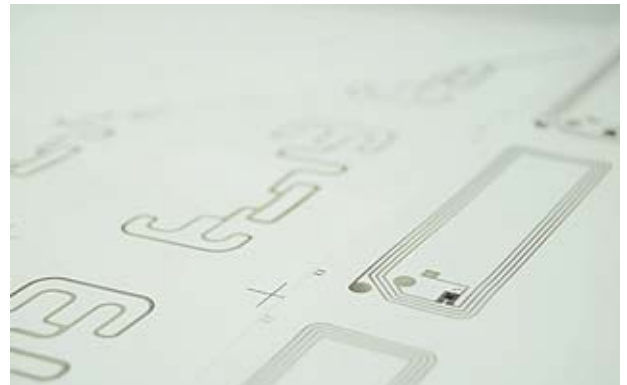


## Teslin® Prelaminate

### ISO 14443

- High card surface quality without dents and dimples and good printability
- Based on Flip-Chip technology with KSW Palladium Bumping
- Consistent reproducible antenna geometries and read range



#### Applications

#### eGovernment

eID cards, ePassport (e.g. for passport data pages) eDrivers license, border control

#### Specifications

<b>Product thickness</b> with IC	approx. 550µm	<b>Integrated Circuit</b>	NXP Mifare family NXP SmartMX family
<b>Substrate</b>	Teslin®, white		
<b>Antenna</b>	conductive silver ink		(Chip alternatives upon request)
<b>Operating frequency</b>	13,56MHz	<b>Delivery form</b>	all common card industry formats  max. sheet format 56up

#### Features and Options

**Reliability:** acc. to ISO 10373-1

For further information please contact the KSW Sales or Customer Service Team:  
E-Mail: [sales@ksw-microtec.de](mailto:sales@ksw-microtec.de) | Web: [www.ksw-microtec.de](http://www.ksw-microtec.de) | Phone.: +49 351 88 960 10